



TECHNICAL DATA

U_{max}	2.1 V	$T_{hot} = 25^\circ\text{C}$ Vacuum
Q_{max}	1.83 W	
ΔT_{max}	72°	
I_{max}	1.5 A	
ACR at 25°C	1.24 Ohm	
Lead wires type	Cu wire Sn plated $\phi 0.3$ mm	
Solder	Lead Free, m.p.t. $\geq 227^\circ\text{C}$	
Hot side	Ceramics Al_2O_3 , white 96%	
Cold side		
Maximum processing temperature 180°C		
Tolerances for thermal and electrical parameters $\pm 10\%$		
This product is compliant to RoHS (2002/95/EC)		

AVAILABLE MODIFICATIONS

Design	Description
TM-18-0.6-1.5	Porch-style design without metallization

MODIFICATIONS UPON REQUEST

Design	Description
TM-18-0.6-1.5 T	Porch-style design with metallization on the hot side
TM-18-0.6-1.5 TT	Porch-style design with metallization on both sides

STANDARD ORDERING OPTIONS

N°	Option	Parameter
1	Lead wires length	$L \geq 30$ mm
2	Lead wires insulation	Maximum processing temperature
	Without insulation	200°C
	Silicone (<24 AWG)	180°C
3	Sealing	Maximum processing temperature
	No sealing	200°C
	Epoxy	130°C
	Silicone	180°C

OPTIONS UPON REQUEST

Height tolerance	± 0.05 *
Unflatness and nonparallelism	± 0.02 *
Anticorrosion coating	

* These options are available only for module design without metallization on external sides.

For another options consult of our technical support engineers

Notes

- When applying plus voltage to positive lead wire the module cold side becomes heat absorbing surface.
- Module AC resistance at 25°C does not include resistance of lead wires.

Performance graphs for TM-18-0.6-1.5 modules at Th=25 °C
 Environment: vacuum

